



## 即时发布：

### 先进封装：半导体变革的游戏规则颠覆者 先进封装与系统集成技术研讨会 – 4月22至23日 – 中国上海

来源：《扇外型封装：技术与市场趋势》报告，Yole Développement 公司，2019年



法国里昂讯—2019年4月4日：对更佳的集成的需求、摩尔定律的终结，此外再加上大趋势、交通运输、5G、消费应用、存储器和计算型 AI 以及 HPC……在这些因素的推动下，先进封装已进入了它最成功的时代。当今市场由大型 IDM 主导，如英特尔和三星、全球排名前 4 的 OSAT 和拥有封装厂的代工厂——台积电，他们加在一起占据了先进封装市场总份额的 62%。为了回应市场需求，这些领导者正致力于多种多样的新型先进封装平台，如倒装芯片球栅格阵列（flip-chip BGA）、扇外型封装、3D TSV 等等……每个平台都势头强劲，但各具不同的潜力和特性。

几年前，[Yole Développement \(Yole\)](#)和[华进半导体 \(NCAP China\)](#)决定创建一个全世界独一无二的空间，让领先企业分享自己对该产业的愿景、评估新兴平台，并发现商业机遇。

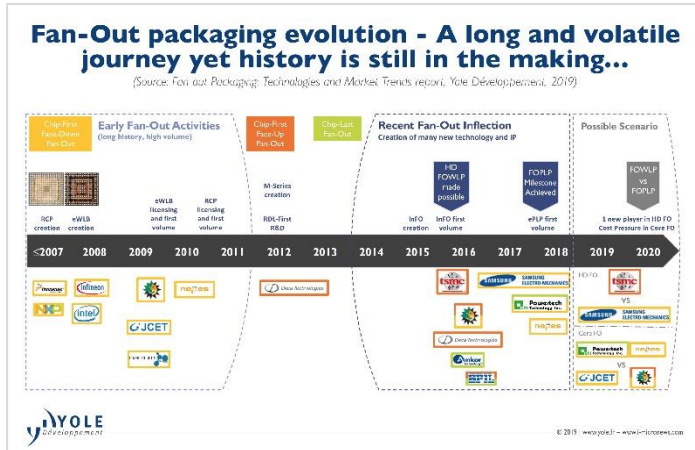


今天，合作双方都确认将成功筹办[第五届先进封装与系统集成技术研讨会](#)。Yole 与华进半导体结合了各自的专业优势，制订出一套与先进封装产业的大趋势影响直接相关的会议活动日程。

先进封装与系统集成技术研讨会将于本月底在上海举行，凭借与业界领先企业和专家之间的

独特纽带，它将展现 5 个业界聚焦的关键领域：AI 与 HPC、存储器与计算、交通运输、5G 和消费应用。组委会将推出约 20 场灵感勃发的讲演、2 场市场简报和多个社交联络环节，涵盖各类主题……

不要错过参与 2019 年研讨会的机会，现在就通过 [i-micronews.com](http://i-micronews.com) 注册！



2015 年，扇外型封装市场规模尚小，且主要由标准器件组成，如 BB、RF 和 PMU。但在台积电于 2016 年为苹果的 iPhone APE 推出颠覆市场的 inFO 后，市场价值截止到 2018 年已增长了 4 倍。于是就出现了 HD 扇外型细分市场，降低了 OSAT 的市场份额。

毫无疑问，目前发展最快的平台就是扇外型封装，其年均复合增长率高达 25%，目标应用也变得多样化，超出了消费领域。不仅如此，扇外型封装

在今年似乎再一次成为最有活力的技术之一，尽管它还需要一波新的成本削减才能传播得更广。有了在面板尺寸方面的努力，一旦业界攻克了强大的挑战，这个目标就能实现。截止到 2024 年，扇外型市场价值将达到近 38 亿美元。

此次先进封装与系统集成技术研讨会的活动日程贴合产业进化和新兴创新技术。考虑到扇外型封装市场的吸引力，Yole 和华进半导体将围绕这一先进封装平台推出多场令人印象深刻的讲演：**Bosch Sensortec 中国分公司的业务开发与市场营销总监 Fu Bin 女士**将以传感器解决方案创新者的身份，深入剖析更加智能的传感器可如何促进物联网的前沿趋势。

与此同时，**Broadpak 的总经理兼首席技术官 Farhang Yazdani**将作关于 AI 与 HPC 大趋势的专题讲演：“半导体产业正处在一个转折点：CMOS 尺寸增长步伐放缓和成本增加促使该产业依赖于 IC 封装产业，以扩展‘不止是摩尔’时代的利益。”

借此机会，上海研讨会将迎来领先企业的讲演者：

*Amkor Technology、AT&S China、BESI、Bosch Sensortec、Boschman Advanced Packaging Technology、Brewer Science、Broadpak、China WLCSP、ERS electronic、JVCET、KLA、Kulicke & Soffa、NCAP China、SiPlus、SPIL、System Plus Consulting、TDK InvenSense、TD-Sien Integrated Circuit、Unisoc、Visionox Technology、Xilinx 和 Yole Développement.*

此外，2019 年研讨会将由以下公司支持：

*SPTS Technologies、an Orbotech Company、ULVAC、Besi、Bowman、Hanmi、ERS Electronic、Kulicke & Soffa 和 ASM Assembly Systems.*

Yole Développement 的封装和基板分析师们诚邀您深入了解产业进化和技术问题，我们将聚焦 AI 与 HPC、存储器与计算、交通运输、消费应用和 5G，并带来两场专门市场的简报，简报内容由 Yole 的半导体与软件团队编制的：**Emilie Jolivet - 半导体与软件部总监、Favier Shoo - 技术与市场分析师，和 Santosh Kumar**

-高级分析师兼 Yole 韩国封装、组装与基板总监、以及首席执行官 **Thibault Buisson**。

他们将介绍在对创新技术和颠覆性技术的需求下兴起的新型生态系统。分析师们也将详细说明产业进化及其对供应链上的每一环产生的影响。

一个激动人心又充满活力的时代即将到来。欢迎来到半导体的新世界！

可通过 [i-micronews.com](http://i-micronews.com) 注册并赞助本次研讨会。

**ABOUT THE REPORT:****Fan-Out Packaging: Technologies and Market Trends 2019**

*Samsung and PTI, with panel-level packaging, have entered the Fan-Out battlefield.* – Produced by Yole Développement (Yole).

**Companies cited in the report:**

3D-Plus, 3M, AGC, Amkor, Analog Devices, Akrometrix, Apple, Applied Materials, ASE, ASM, A\*Star, Aurora Semiconductors, Besi, Boschmann, Brewer Science, Broadcom, Bosch, Camtek, Corning, Dialog Semiconductor, Dow, Evatec, EVGroup, Fico Molding, Freescale (NXP), Fujifilm, HD Microsystems, Henkel, Hi Silicon, Huawei, Huatian, Hitachi Chemicals, Hoya, Ibiden, IME, Infineon, Intel, ITRI, JSR, Lintec, Mediatek, Medtronic, Mitsui Chemicals... [Full list](#)

**Author:**

**Favier Shoo** is a Technology and Market Analyst in the Semiconductor & Software division at Yole Développement, part of Yole Group of Companies. Favier is engaged in the development of technology & market reports as well as the production of custom consulting. After spending 7 years at Applied Materials as a Customer-Application-Technologist in advanced packaging marketplace, Favier had developed a deep understanding of the supply chain and core business values. Being knowledgeable in this field, Favier had given trainings and held numerous technical review sessions with industry players. In addition, he had obtained 2 patents.

Prior to that, Favier had worked at REC Solar as a Manufacturing Engineer to maximize production capacity. Favier holds a Bachelor in Materials Engineering (Hons) and a Minor in Entrepreneurship from Nanyang Technological University (NTU) (Singapore). Favier was also the co-founder of a startup company where he formulated business goals, revenue models and marketing plans.

**ABOUT NCAP**

The National Center for Advanced Packaging Co., Ltd. (NCAP China) is a joint venture established by ten investors, including the leaders of the IC packaging and testing industry in China. NCAP's goal is to establish a world class R&D center for advanced packaging and system integration, play a leading role in the development and marketing of advanced technologies for microelectronics packaging and system integration, and promote and sustain the technological and commercial progress of the microelectronics industry in China.

As a national center for advanced packaging, testing and system integration, NCAP, in collaboration with system OEMs and supply chain partners, aggressively pursues research and development in order to offer complete solutions for the IC industry. NCAP's current research areas include: 2.5D/3D technology (including TSV), high-density wafer level packaging, SiP product development capabilities, and certain advanced materials and equipment technologies for microelectronics packaging.

The NCAP R&D platform includes a 3200-m<sup>2</sup> fully equipped cleanroom, for 300mm wafer size, for 2.5D/3D IC backend processes, and packaging assembly, testing and reliability, as well as design and simulation capabilities. More information on [www.ncap-cn.com](http://www.ncap-cn.com).

**ABOUT YOLE DEVELOPPEMENT**

Founded in 1998, Yole Développement (Yole) has grown to become a group of companies providing marketing, technology and strategy consulting, media and corporate finance services, reverse engineering and reverse costing services and well as IP and patent analysis. With a strong focus on emerging applications using silicon and/or micro manufacturing, the Yole group of companies has expanded to include more than 80 collaborators worldwide covering MEMS & Sensors - Imaging - Medical Technologies - Compound Semiconductors - RF Electronics - Solid State Lighting - Displays - Photonics - Power Electronics - Batteries & Energy Management - Advanced Packaging - Semiconductor Manufacturing - Software & Computing and more...

The “More than Moore” market research, technology and strategy consulting company Yole Développement, along with its partners System Plus Consulting, PISEO and KnowMade, support industrial companies, investors and R&D organizations worldwide to help them understand markets and follow technology trends to grow their business. For more information, visit [www.yole.fr](http://www.yole.fr) and follow Yole on [LinkedIn](#) and [Twitter](#).

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